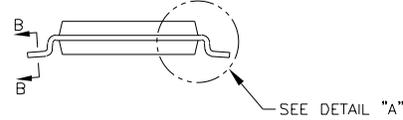
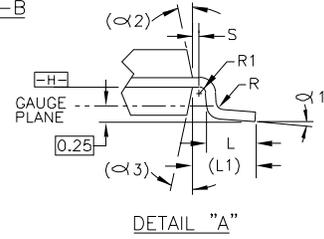
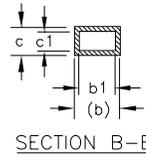
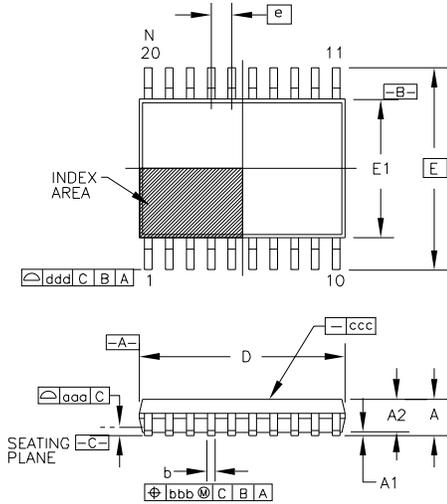


Package Number 353 - 20-Lead TSSOP, .173 Wide



DIM	INCHES		MILLIMETERS		N	E	DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.				MIN.	MAX.	MIN.	MAX.		
A	--	.047	--	1.20			R	.004	--	0.09	--		
A1	.002	.006	0.05	0.15			R1	.004	--	0.09	--		
A2	.031	.041	0.80	1.05			S	.008	--	0.20	--		
b	.007	.012	0.19	0.30	5		aaa	.004	NOM.	0.10	NOM.		
b1	.007	.010	0.19	0.25			bbb	.004	NOM.	0.10	NOM.		
c	.004	.008	0.09	0.20			ccc	.002	NOM.	0.05	NOM.		
c1	.004	.006	0.09	0.16			ddd	.008	NOM.	0.20	NOM.		
D	.252	.260	6.40	6.60	3.8		alpha 1	0°	8°	0°	8°		
E	.252	BASIC	6.40	BASIC			alpha 2	12°	REF.	12°	REF.		
E1	.169	.177	4.30	4.50	4.8		alpha 3	12°	REF.	12°	REF.		
e	.0256	BASIC	0.65	BASIC									
L	.018	.030	0.45	0.75									
L1	.039	REF.	1.00	REF.									
N	20		20		6								

- NOTES:
1. MILLIMETERS SHALL BE CONTROLLING UNIT.
 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 3. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm (.006 IN) PER SIDE.
 4. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25mm(.010 IN) PER SIDE.
 5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm(.003 IN) TOTAL IN EXCESS OF THE b DIMENSION

- AT MAXIMUM MATERIAL CONDITION, DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07mm(.003 IN).
6. N IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS.
 7. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
 8. DIMENSIONS D AND E1 TO BE DETERMINED AT DATUM PLANE -H-.
 9. SECTION B-B TO BE DETERMINED AT 0.10mm TO 0.25mm FROM LEAD TIP.
 10. PIN 1 IDENTIFIER MUST BE LOCATED WITHIN THE CROSSHATCHED INDEX AREA.

PACKAGE NUMBER: ZZ353 REV.: B
JEDEC NUMBER: MO-153-AC

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